



US00D834544S

(12) **United States Design Patent** (10) **Patent No.:** **US D834,544 S**  
**Kurz** (45) **Date of Patent:** **\*\* Nov. 27, 2018**

(54) **SEMICONDUCTOR MODULE** 7,397,668 B2 \* 7/2008 Sekine ..... H05K 7/1465  
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(71) Applicant: **Infineon Technologies AG**, Neubiberg D621,351 S 8/2010 Huang et al.  
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(72) Inventor: **Dorian Kurz**, Solingen (DE) 9,099,256 B2 \* 8/2015 Gole  
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(73) Assignee: **Infineon Technologies AG**, Neubiberg D763,201 S \* 8/2016 Burkell ..... D13/162  
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(\*\*) Term: **15 Years** 2012/0109343 A1 \* 5/2012 Shah ..... G05B 19/409  
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(21) Appl. No.: **29/541,134**

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(22) Filed: **Sep. 30, 2015**

*Primary Examiner* — Angela J Lee  
*Assistant Examiner* — Shawn T Gingrich

(30) **Foreign Application Priority Data**

(74) *Attorney, Agent, or Firm* — Murphy, Bilak & Homiller, PLLC

Apr. 1, 2015 (EM) ..... 002673699

(51) **LOC (11) Cl.** ..... **13-03**

(57) **CLAIM**

(52) **U.S. Cl.**  
USPC ..... **D13/182**; D13/158

The ornamental design for a semiconductor module, as shown and described.

(58) **Field of Classification Search**  
USPC ..... D13/101, 110, 118, 123, 158–162, 173,  
D13/182, 184, 199  
CPC . G05B 15/00; H01H 9/00; H01H 9/02; H01H  
9/22; H01H 13/00; H01L 23/48; H01L  
23/49; H01L 23/52; H01L 25/07; H01R  
13/00; H01R 13/60; H02B 1/00  
See application file for complete search history.

**DESCRIPTION**

(56) **References Cited**

FIG. 1 is a top, front and right side perspective view of the semiconductor module showing my new design; FIG. 2 is a back side elevational view thereof; FIG. 3 is a front side elevational view thereof; FIG. 4 is a left side elevational view thereof; FIG. 5 is a right side elevational view thereof; and, FIG. 6 is a top plan view thereof.

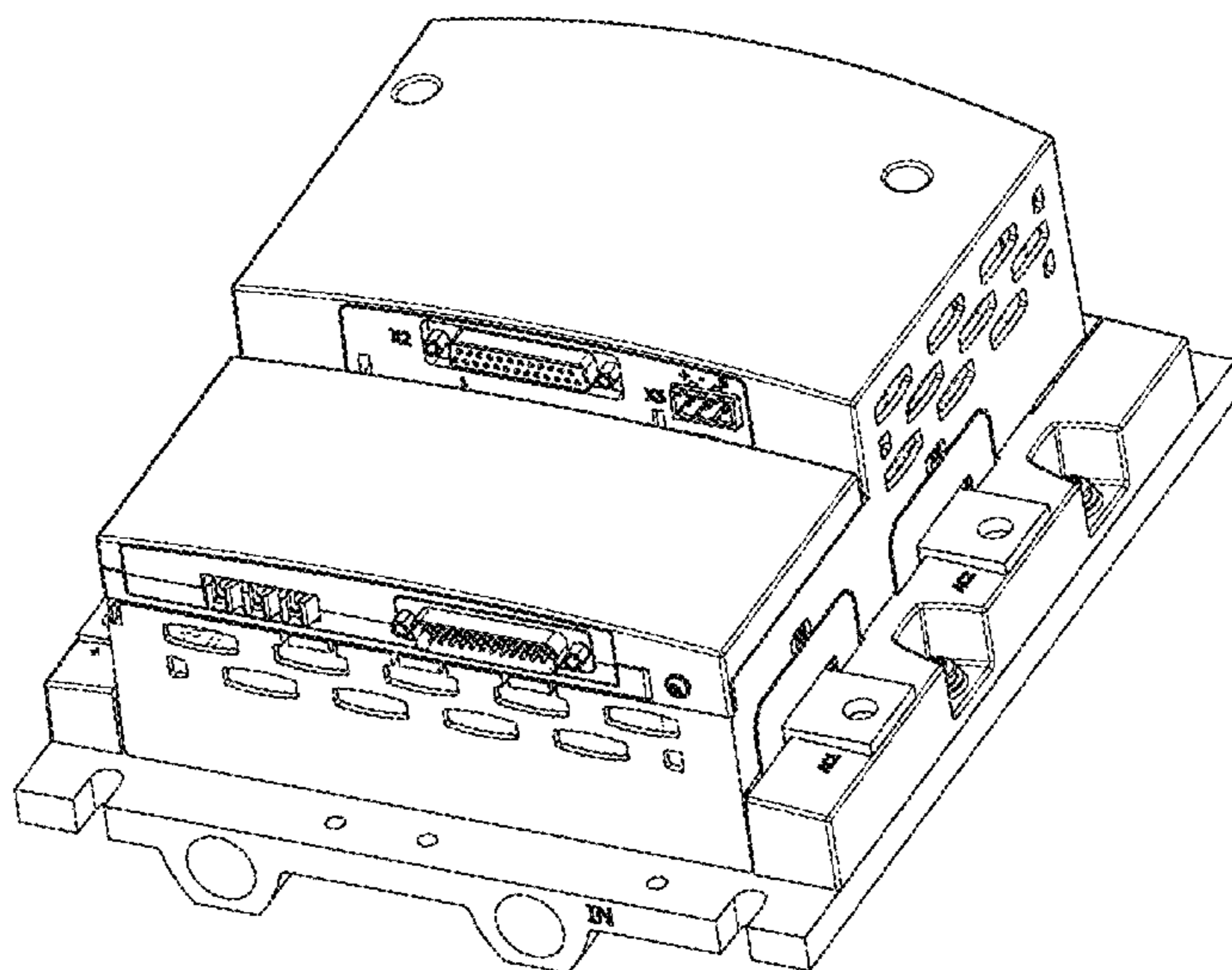
**U.S. PATENT DOCUMENTS**

The broken line portion of the figure drawings is included to show portions of the article that form no part of the claimed design.

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All surfaces not shown form no part of the claimed design.

**1 Claim, 6 Drawing Sheets**



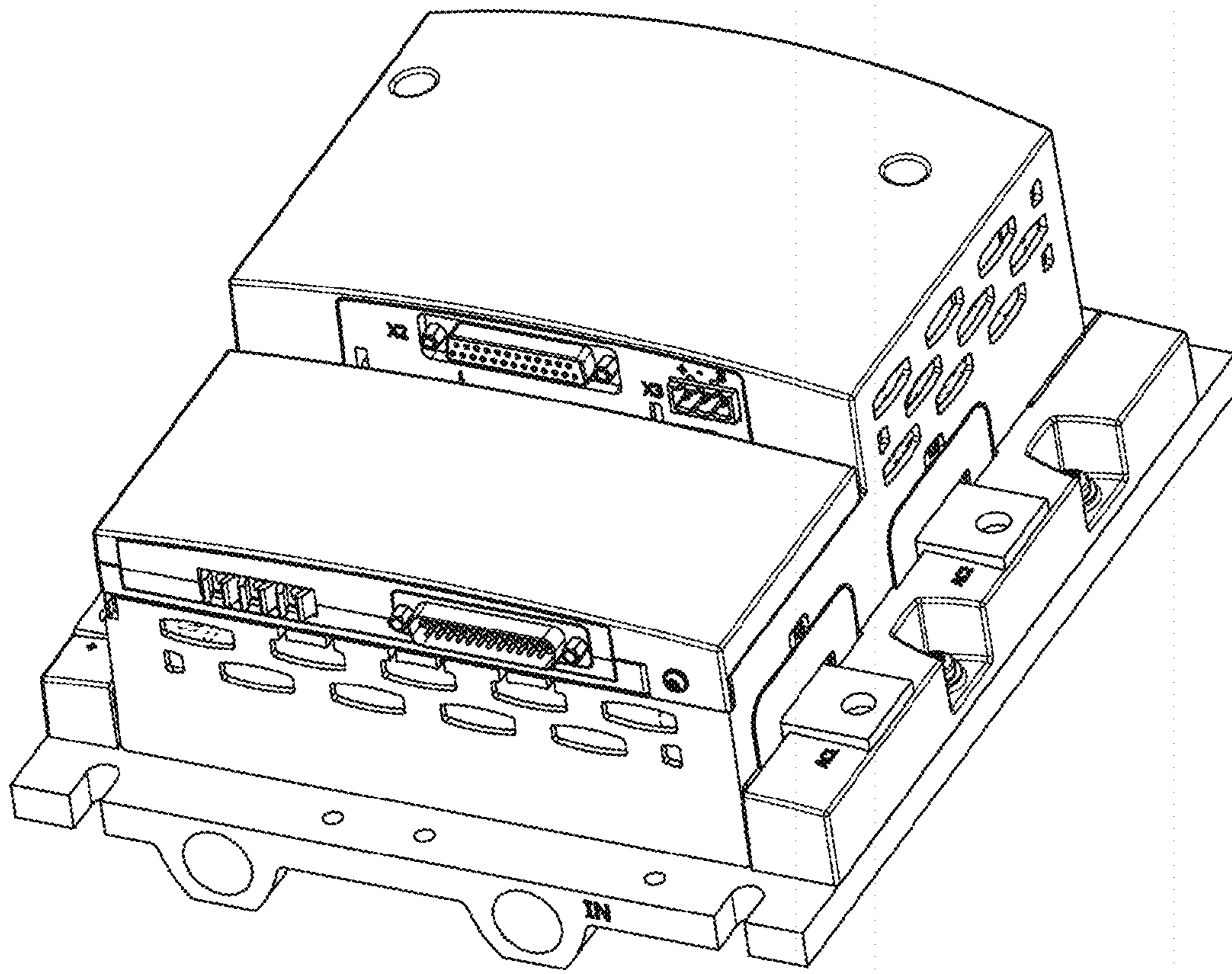


FIG. 1

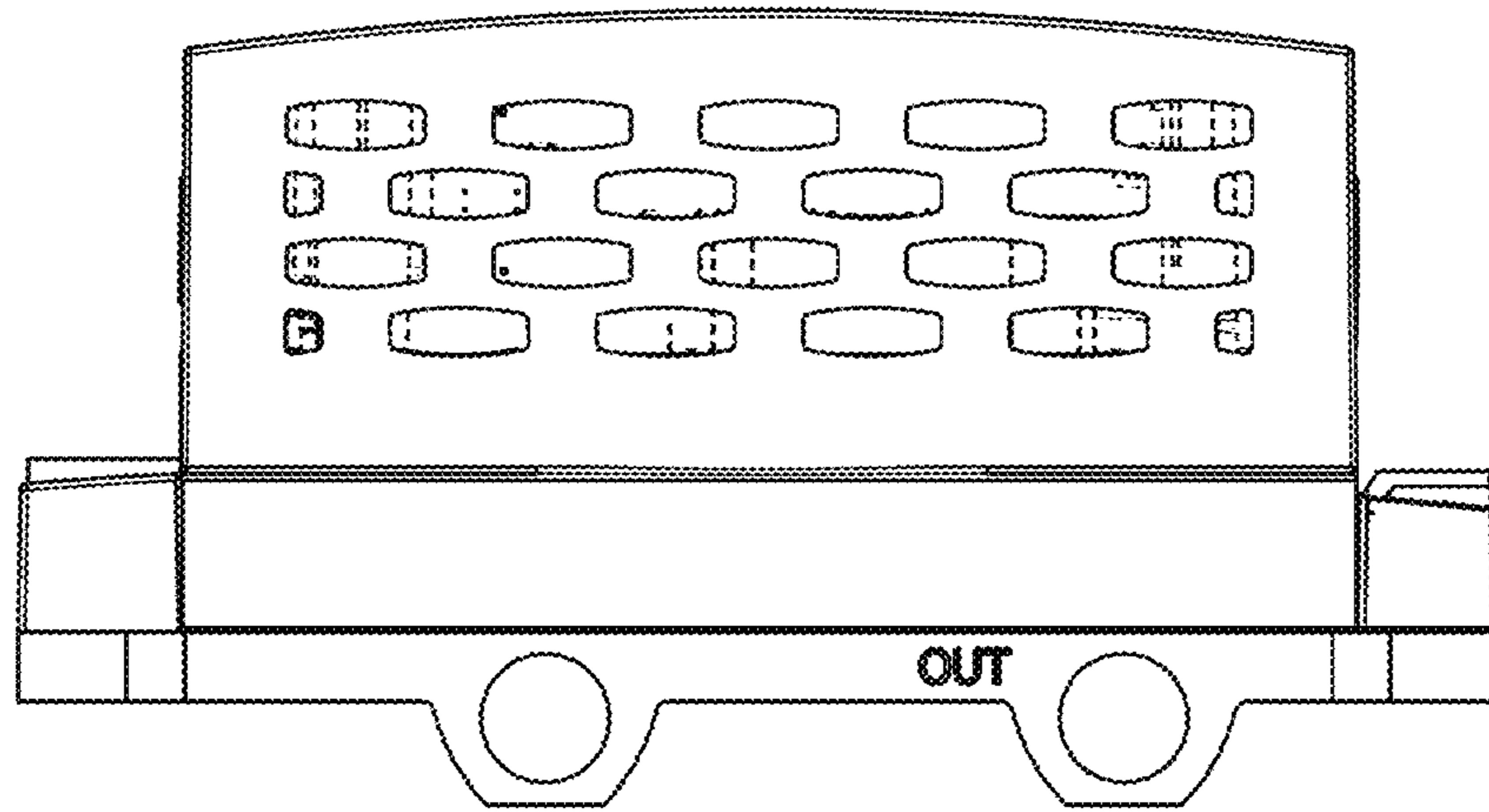


FIG. 2

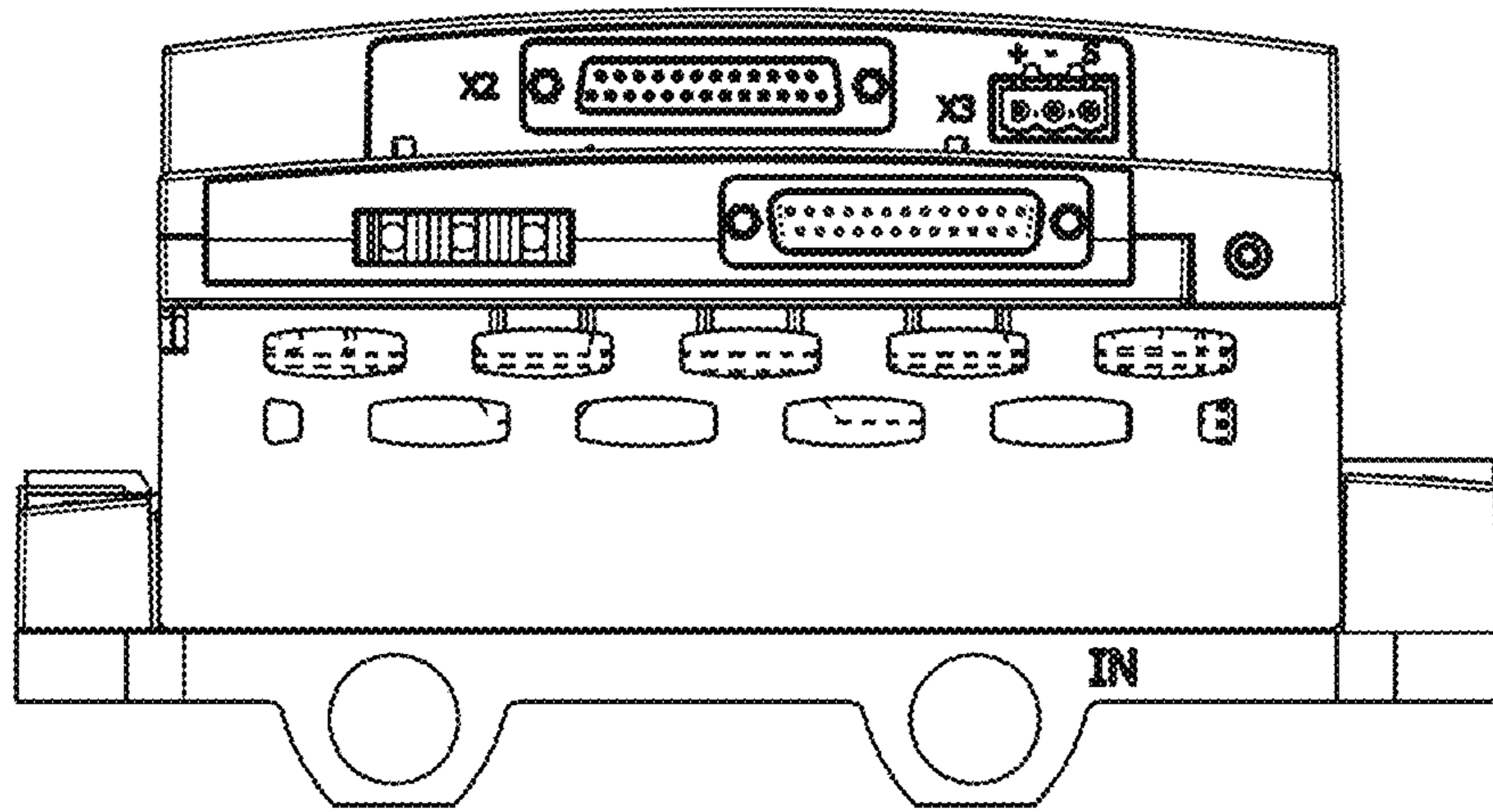


FIG. 3

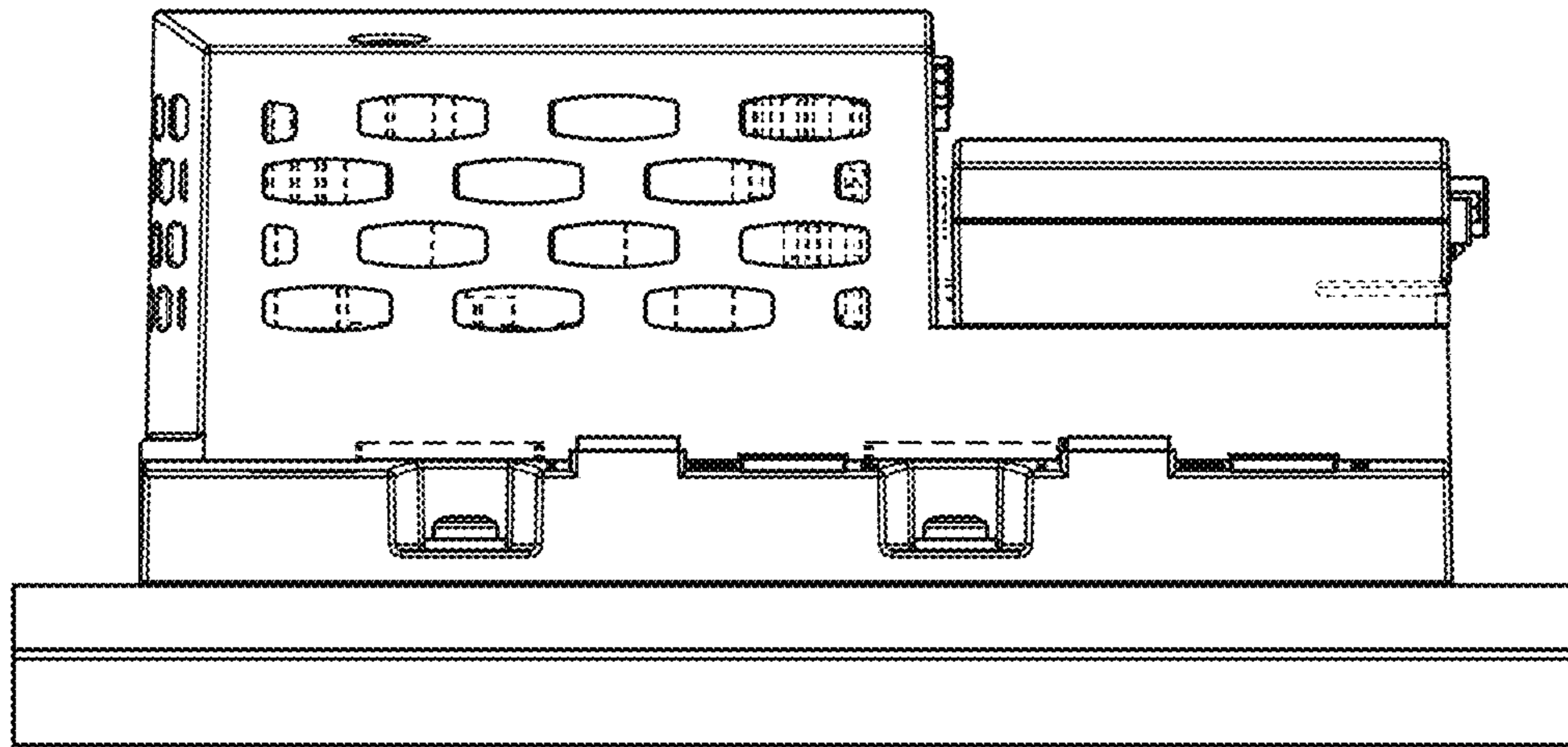


FIG. 4

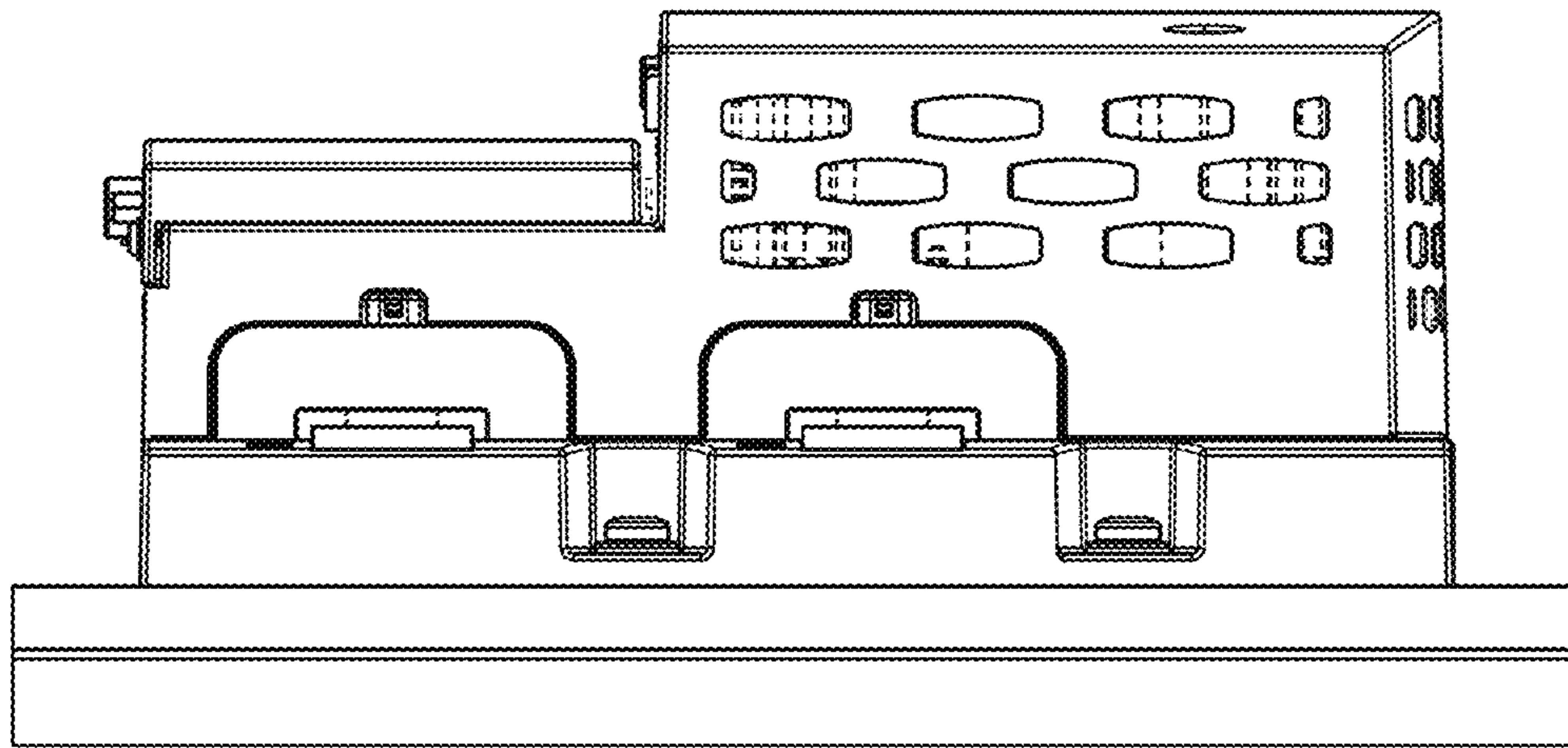


FIG. 5

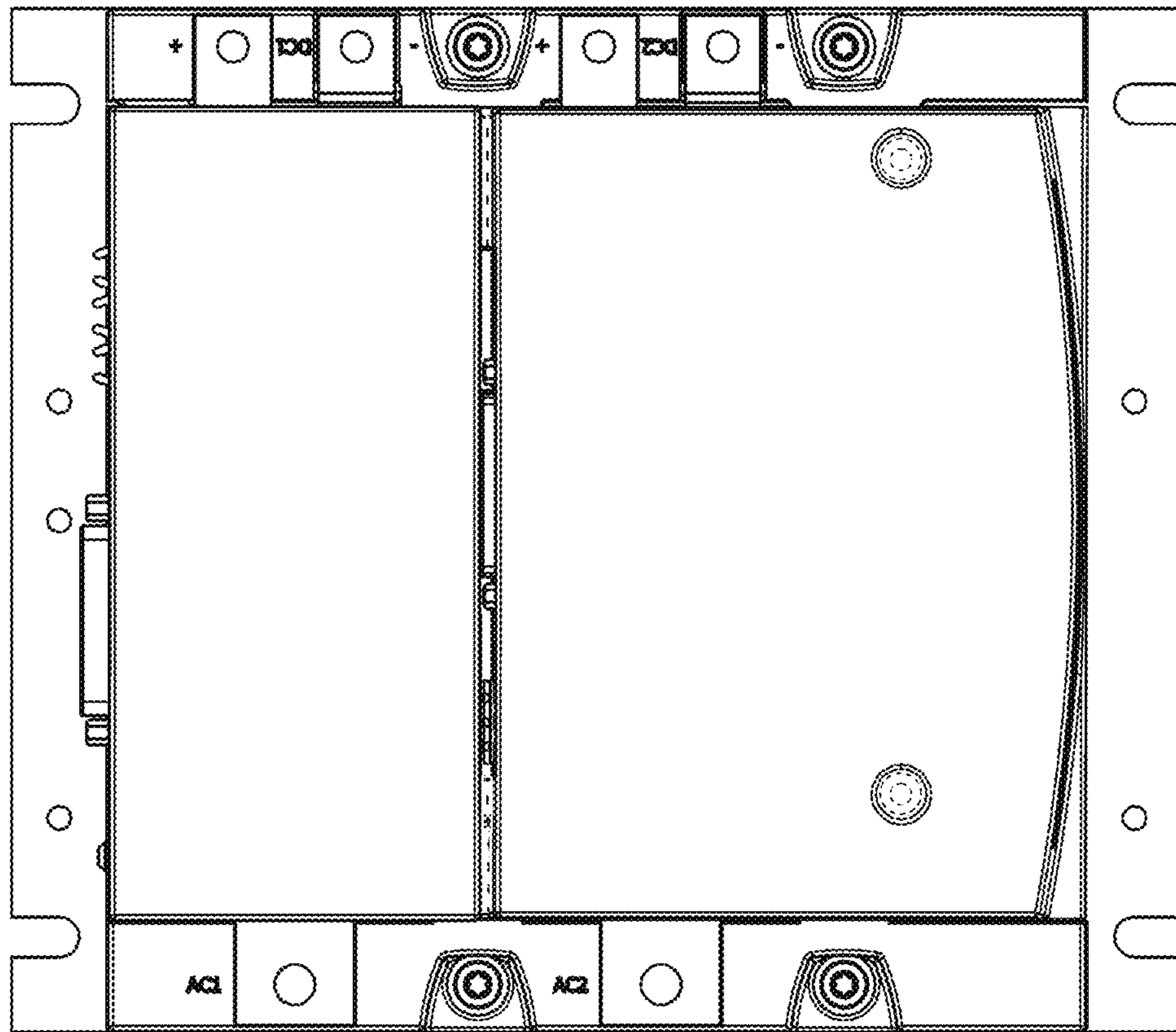


FIG. 6